



ADS52J90 8/16/32-Channel, Analog-to-Digital Converter Evaluation Module

This user's guide gives an overview of the evaluation module (EVM) and provides a general description of the features and functions to be considered while using this module. This manual is applicable to the ADS52J90 analog-to-digital converters (ADC). The ADS52J90 EVM provides a platform for evaluating the ADC under various signal, clock, reference, and ADC output formats. In addition, the EVM supports the testing of both an LVDS interface as well as a JESD204B interface.

NOTE: A different capture card EVM is required for each.

Contents

1	Quick Views of Evaluation Setups for LVDS and JESD204B Interfaces	3
1.1	LVDS Interface (ADS52J90 EVM + TSW1400).....	3
1.2	JESD204B Interface (ADS52J90 EVM + TSW14J56)	4
2	GUI Software Installation	5
2.1	High Speed Data Converter Pro (HSDCpro) GUI Installation	5
2.2	ADS52J90 GUI Installation (HMC-DAQ).....	5
3	ADS52J90 EVM Headers/Test Points and Clock Configuration.....	6
3.1	ADS52J90 EVM Header Configuration	6
3.2	ADS52J90 EVM Test points.....	7
3.3	EVM Clock Configuration	8
4	Quick Test LVDS Interface	9
4.1	EVM Layout and Hardware Setup	9
4.2	Capturing Ramp Test Pattern and Sinusoidal Input	12
4.3	Testing All Modes of the Device.....	24

List of Figures

1	LVDS Evaluation Setup	3
2	JESD204B Evaluation Setup	4
3	Clock Config: LMK CDM Mode	8
4	HSDCpro 40x Lane Rate Message	9
5	HSDCpro 10x Lane Rate Message	9
6	ADS52J90 EVM Analog Channels	10
7	TSW1400 and ADS52J90 Setup	11
8	TSW1400 GUI Setup (a)	12
9	TSW1400 GUI Setup (b)	13
10	TSW1400 GUI Setup (c)	13
11	TSW1400 GUI Setup (d)	14
12	TSW1400 GUI Setup (e)	14
13	TSW1400 GUI Setup (f)	15
14	HMC-DAQ GUI Setup (a)	15
15	HMC-DAQ GUI Setup (b)	16

16	HMC-DAQ GUI Setup (c)	16
17	HMC-DAQ GUI Setup (d)	17
18	ADS52J90 16-Channel RAMP Capture (a)	18
19	ADS52J90 16-Channel RAMP Capture (b)	19
20	ADS52J90 16-Channel RAMP Capture (c)	19
21	ADS52J90 16-Channel RAMP Capture (d)	20
22	ADS52J90 16-Channel SINE Capture (a)	21
23	ADS52J90 16-Channel SINE Capture (b)	22
24	ADS52J90 16-Channel SINE Capture (c)	23
25	ADS52J90 All Supported Configs	24
26	ADS52J90 All Supported Configs (b)	25
27	ADS52J90 All Supported Configs (c)	26

List of Tables

1	ADS52J90 Default Header Configuration.....	6
2	ADS52J90 EVM Test Points	7

1 Quick Views of Evaluation Setups for LVDS and JESD204B Interfaces

The ADS52J90 EVM can be tested using an LVDS data interface or a JESD204B data interface.

1.1 LVDS Interface (ADS52J90 EVM + TSW1400)

As shown in Figure 1, mating the ADS52J90 EVM with a TSW1400 EVM allows testing using an LVDS data interface.

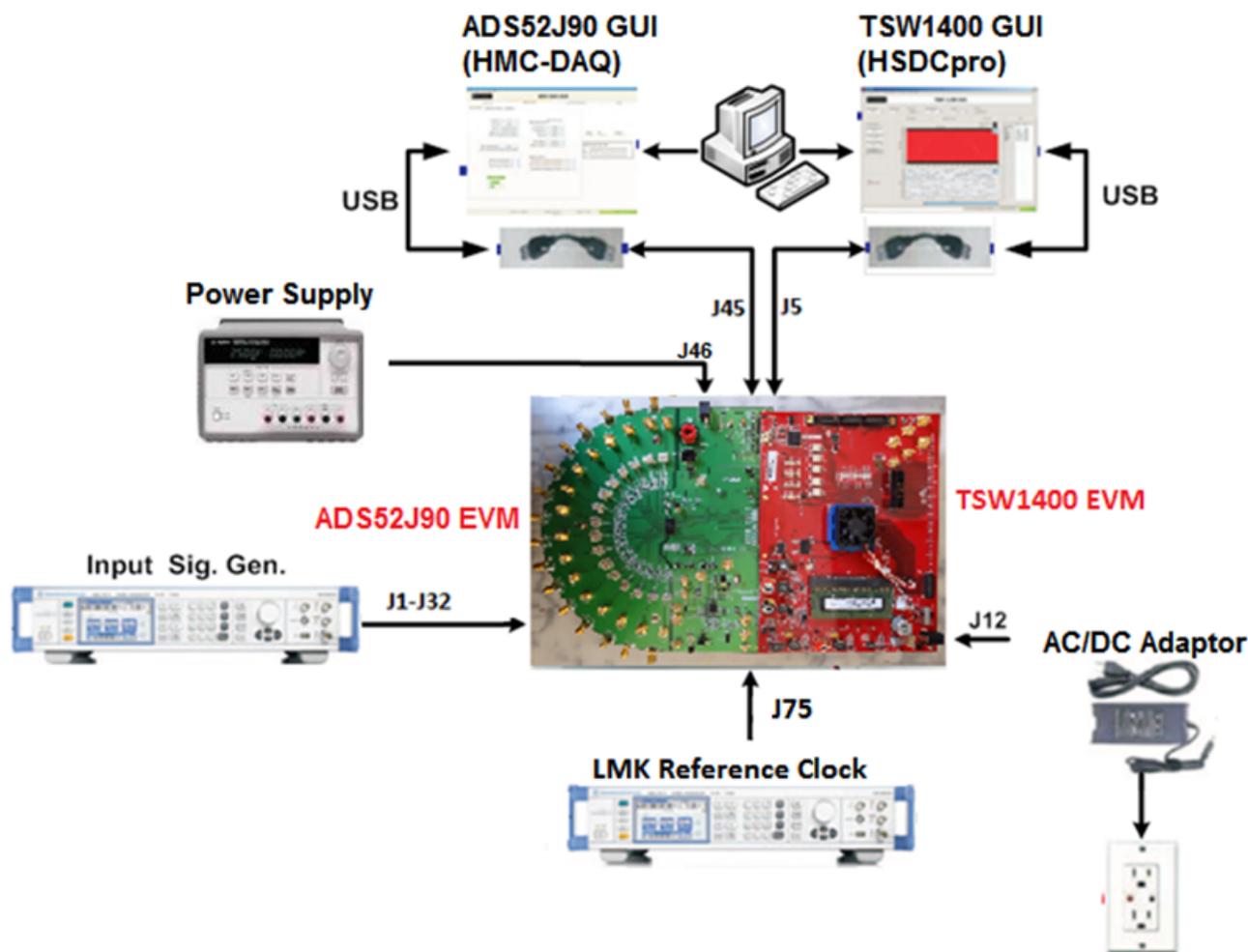


Figure 1. LVDS Evaluation Setup

FPGA EVM: The TSW1400 high-speed LVDS de-serializer EVM is required for capturing data from the ADS52J90EVM. Analysis of the captured data is possible using its graphical user interface (GUI) which is called High Speed Data Converter Pro.

NOTE: The same GUI is used to control the TSW14J56 capture card for supporting a JESD204B data interface.

For more information pertaining to be TSW1400EVM, see:
<http://focus.ti.com/docs/toolsw/folders/print/tsw1400evm.html>.

Equipment: Signal generators (with low-phase noise) must be used as source of input signal and clock in order to get the desired performance. Additionally, a band-pass filter (BPF) is required on the analog input signal to attenuate the harmonics and noise from the generators.

Power Supply: A single +5-V supply powers the ADS52J90EVM through connectors located at **J47** and **J48** or through an AC adaptor (not provided) at **J46**. The supply for the ADS52J90 device is derived from this +5-V supply. The power supply must be able to source up to 1.5 A. The TSW1400 EVM is powered through an AC adaptor provided with its EVM kit.

USB Interface to PC: The USB connections from the ADS52J90EVM and TSW1400EVM to the computer are used for communication from the GUIs to the boards. [Section 2](#) explains the *High Speed Data Converter Pro* and ADS52J90 GUI installation procedures.

1.2 JESD204B Interface (ADS52J90 EVM + TSW14J56)

As shown in [Figure 2](#), mating the ADS52J90 EVM with a TSW14J56 EVM allows testing using a JESD204B data interface.

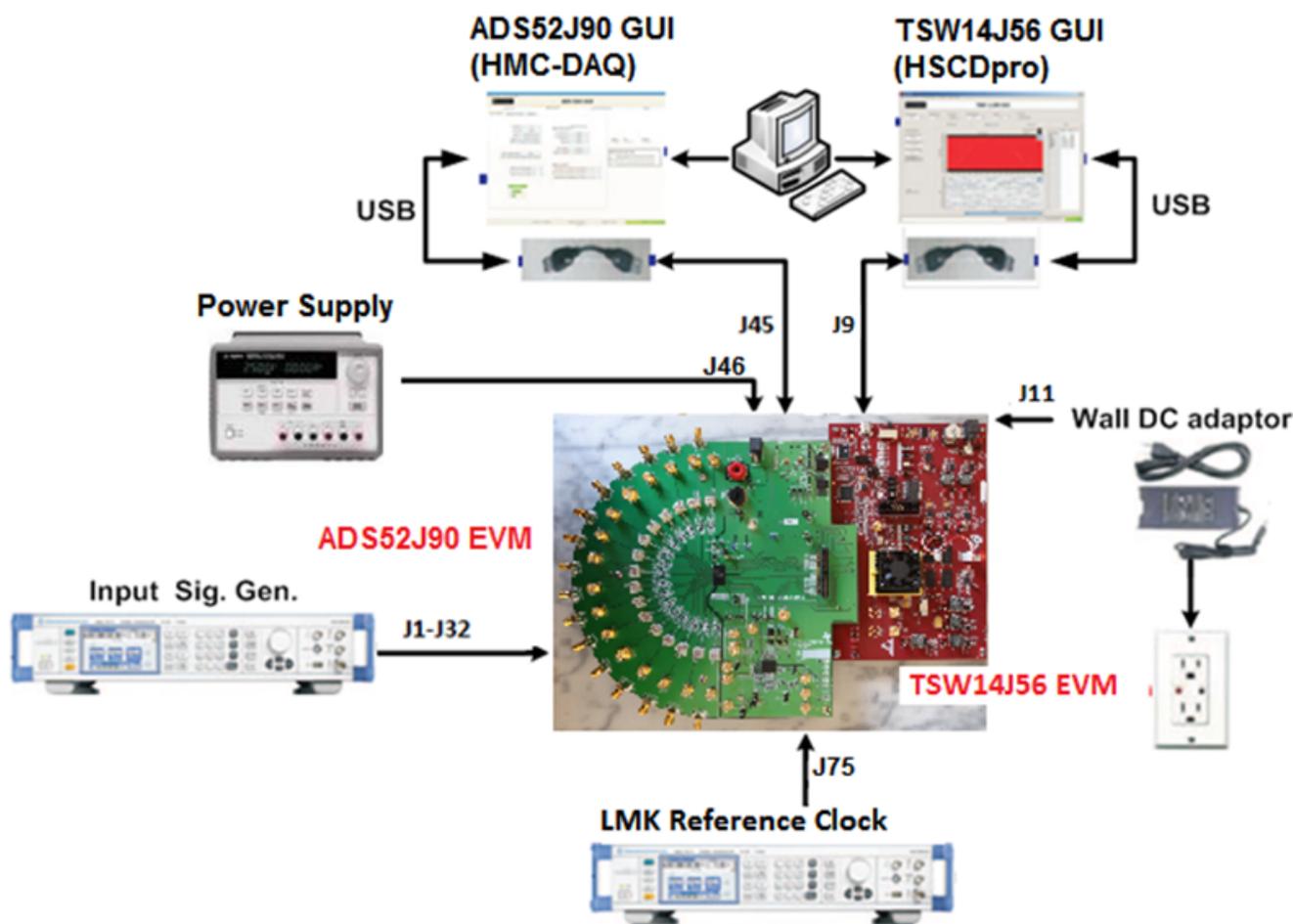


Figure 2. JESD204B Evaluation Setup

FPGA EVM: The TSW14J56 high-speed JESD204B de-serializer board is required for capturing data from the ADS52J90EVM. Analysis of the captured data is possible using its graphical user interface (GUI) which is called High Speed Data Converter Pro (*note: the same GUI is used to control the TSW1400 capture card for supporting an LVDS data interface*).

For more information pertaining to the TSW14J56EVM, see: <http://www.ti.com/tool/tsw14j56evm>

Equipment: Signal generators (with low-phase noise) must be used as source of input signal and clock in order to get the desired performance. Additionally, a band-pass filter (BPF) is required on the analog input signal to attenuate the harmonics and noise from the generator.

Power Supply: A single +5-V supply powers the ADS52J90EVM through connectors located at **J47** and **J48** or through an AC adaptor (not provided) at **J46**. The supply for the ADS52J90 device is derived from this +5-V supply. The power supply must be able to source up to 1.5 A. The TSW14J56 EVM is powered through an AC adaptor provided with its EVM kit.

USB Interface to PC: The USB connections from the ADS52J90EVM and TSW14J56EVM to the computer are used for communication from the GUIs to the boards. [Section 2](#) explains the *High Speed Data Converter Pro* and ADS52J90 GUI installation procedures.

2 GUI Software Installation

The ADS52J90 EVM and the de-serializing capture card EVM both require software installations. The following two sections explain where to find and how to install the software properly. Ensure that no USB connections are made to the EVMs until after the installations are complete.

2.1 High Speed Data Converter Pro (HSDCpro) GUI Installation

Download the [High Speed Data Converter Pro GUI Installer \(SLWC107\)](#) from the Texas Instruments website (www.ti.com) and install per the instructions in its user's guide ([SLWU087](#)).

NOTE: Version 3.1 or higher of HSDC Pro is required to test the ADS52J0. If an earlier version of HSDC Pro is installed, please uninstall before installing the latest version.

TI recommends installing HSDC Pro before installing the ADS52J90 GUI and installing it in the default location provided during installation.

2.2 ADS52J90 GUI Installation (HMC-DAQ)

The GUI used to control the ADS52J90 EVM is a suite that supports a family of devices. The GUI is called *Healthtech Multi-Channel Data Acquisition GUI*, or, *HMC-DAQ*. Download and save the file *HMC-DAQ_GUI_INSTALLER_SLOC326.zip* to a temporary location on the local PC hard drive. Once saved, unzip the file and run the executable as administrator by right clicking on the file. Follow the instructions provided during installation. TI recommends installing after HSDCpro has been installed and in the default location provided during installation.

3 ADS52J90 EVM Headers/Test Points and Clock Configuration

This section describes the functions of the headers on the EVM. It also provides a list of test points on the EVM that are useful for debug and general-use purposes. Finally, several options for providing clocks to the EVM are described.

3.1 ADS52J90 EVM Header Configuration

The ADS52J90 EVM is flexible in its configurability through the use of 2- and 3-pin headers. [Table 1](#) describes the purpose of all headers on the EVM and the default positions. With this configuration, all required clocks for testing the LVDS or JESD204B interface are derived from a single reference clock provided to SMA J75 to the LMK04826 clocking device installed at designator **U2** on the EVM. The LMK04826 is configured for Clock Distribution Mode (CDM) with the provided scripts.

Table 1. ADS52J90 Default Header Configuration

Jumper Description	Jumper#	Jumper Name	Default Config	Circuit	Description
Power Supply	JP9	+3.3VCLK	Short pins 1-2	Clocks	Power supply XTAL1, XTAL2, OSC1, LMK04826
	JP10	IOVDD_+3.3V	Short pins 1-2	SPI BUFFERS	Power supply for SPI level shifters and isolators
	JP11	DVDD_+1.2V	Short pins 1-2	ADS52JD90	+1.2-V digital power supply for ADS52JD90
	JP12	AVDD_+1.8V	Short pins 1-2	ADS52JD90	+1.8-V analog power supply for ADS52JD90
	JP13	LVDD_+1.8V	Short pins 1-2	ADS52JD90	+1.8-V digital power supply for ADS52JD90
	JP15	DISABLE	DNI	Regulator	Not used
	JP16	5VIN	DNI	Regulator	Not used
ADS52J90 SYNC Options	JP33	n/a	Short pins 1-2	ADS52JD90 SYNC pin	Selects SYNC signal source to ADS52JD90: (1) Auxiliary signal determined by JP28 or (3) GUI via FTDI device
	JP28	n/a	Short pins 1-2	ADS52JD90 SYNC pin	Selects auxiliary SYNC signal source to ADS52JD90: (1) SMA J50 or (3) FPGA via pin 105 of connector J44B
LMK04826 Options	JP2	SYNC	Short pins 1-2	LMK SYNC	Selects the source of SYNC signal into LMK042x clock device: (1) signal from SMA J39, LMK_SYNC or (3) signal from FPGA at pin K22 of connector J43C
	JP3	LMK_RB	Short pins 2-3	LMK Readback/Reset	Selects LMK RESET pin signal source: (1) LMK_DATA_OUT out to FTDI (3) LMK_RESET in from FTDI
ADC_CLKP/M SEL	JP39	ADC_CLK_AUX	Short pins 1-2	ADS52J90 CLKP/M & SYSREFP/M Source	Selects auxiliary CLKP/M signal source to ADS52JD90: (1) SMA J55, ADC_CLK or (3) one of two on-board XTAL oscillators determined by JP8
	JP40	ADC_CLK	Short pins 2-3		Selects signal source to CLKP/M of ADS52J90: (1) Auxiliary source from JP39 or (3) LMK04826 output
	JP41	ADC_SYSREF	Short pins 1-2		Selects signal source to CLKP/M of ADS52J90: (1) Auxiliary source from JP39 or (3) LMK04826 output
XTAL Power Supply Options	JP4	OSC1_VDD	Open	XTAL/OSC Power	Powers 100-MHz OSC1
	JP5	XTAL1_VDD	Open		Powers 10-MHz XTAL1
	JP6	XTAL2_VDD	Open		Powers 40-MHz XTAL2
XTAL SEL	JP7	LMK_CLKIN1	Short pins 1-2	LMK CLKIN1	Selects signal source to CLKIN1 of LMK04826: (1) SMA J75, LMK_CLKIN1 or (3) XTAL determined by JP8
	JP8	XTAL_SEL	Open	XTAL Oscillators	Selects XTAL source to JP7 and JP39: (1) 10MHz XTAL1 or (3) 40MHz XTAL2
Analog Inputs 8ch mode	JP700_7	n/a	Short pins 2-3	Analog Inputs 8ch mode	Selects between (1) 5-V power supply and (2) and GND for amplifier on channels 7,8 for 8ch mode
	JP800_8	n/a	Short pins 2-3		

Jumpers **JP11**, **JP12**, **JP13** can be removed and individual power supplies given to these headers in order to monitor the DC current consumed by the ADS52J90.

3.2 ADS52J90 EVM Test points

Table 2 lists all test points on the ADS52J90 EVM and their purposes.

Table 2. ADS52J90 EVM Test Points

Test Point	Silkscreen	Circuit	Description
TP13	+5.0V_IN	Power supply	Main +5-V power supply to EVM
TP15	GND	Power supply	Ground reference for EVM
TP14	IOVDD3.3V	Power supply	Power supply for VCM generation
TP12	+3.3VCLK	Power supply	Power supply for LMK0482x and oscillators
TP16	4V	Power supply	Input supply to regulator at designator U11
TP17	AVDD_+1.8V	Power supply	Power supply to ADS52J90
TP18	LVDD_+1.8V	Power supply	Power supply to ADS52J90
TP19	FORCE_VCM	Analog inputs	Can provide external VCM to analog inputs by installing R108 and uninstalling R110
TP20	FORCE_VREF	Analog inputs	Can provide external VREF to ADS52J90 by installing R109
TP1	VCM	Analog inputs	ADS52J90 output providing VCM to analog inputs
TP4	GTX_CLKP	LMK0428x output	GTX clock to FPGA on capture card
TP5	GTX_CLKM	LMK0428x output	GTX clock to FPGA on capture card
TP21	CLK_LAO_0P	LMK0428x output	Global clock to FPGA on capture card (typ. equals Fs)
TP22	CLK_LAO_0M	LMK0428x output	Global clock to FPGA on capture card (typ. equals Fs)
TP6	SYSREF_P	LMK0428x output	SYSREF clock to FPGA on capture card
TP7	SYSREF_M	LMK0428x output	SYSREF clock to FPGA on capture card
TP8	CLKP	LMK0428x output	Device clock (Fs) to DUT from LMK0482x
TP10	CLKM	LMK0428x output	Device clock (Fs) to DUT from LMK0482x
TP9	SYSREFP	LMK0428x output	SYSREF clock to DUT from LMK0482x
TP11	SYSREFM	LMK0428x output	SYSREF clock to DUT from LMK0482x
TP37	CLK_P	DET LAT EVM	Device clock (Fs) to DUT when Deterministic Latency EVM is used
TP38	CLK_M	DET LAT EVM	Device clock (Fs) to DUT when Deterministic Latency EVM is used
TP35	SYSREF_P	DET LAT EVM	SYSREF clock to DUT when Deterministic Latency EVM is used
TP36	SYSREF_M	DET LAT EVM	SYSREF clock to DUT when Deterministic Latency EVM is used
TP23	GND	GND	Ground reference for EVM
TP2	SYNCP_SERDES	JESD SYNC	Input JESD SYNC~ to ADS52J90 from FPGA
TP3	SYNCM_SERDES	JESD SYNC	Input JESD SYNC~ to ADS52J90 from FPGA
TPA0	SCLK	ADS52J90 SPI PIN	SPI clock input to ADS52J90
TPA1	SDATA	ADS52J90 SPI PIN	SPI data input to ADS52J90
TPA2	SEN	ADS52J90 SPI PIN	SPI enable input to ADS52J90
TPA3	SDOUT	ADS52J90 SPI PIN	SPI read back output from ADS52J90
TPA4	RESET	ADS52J90 PIN	RESET pin to ADS52J90
TPA5	PDN_GBL	ADS52J90 PIN	PDN_GBL pin of ADS52J90
TPA6	PDN_FAST	ADS52J90 PIN	PDN_FAST pin of ADS52J90
TPA7	SYNC_LVDS_FTDI	ADS52J90 PIN	SYNC pin to ADS52J90 allowing for synchronized LVDS outputs
TPB0	LMK_CLK	LMK SPI PIN	SPI clock input to LMK0482x
TPB1	LMK_DATA_OUT	LMK SPI PIN	SPI read back output from LMK0482x
TPB2	LMK_DATA	LMK SPI PIN	SPI data input to LMK0482x
TPB3	LMK_SPI_EN	LMK SPI PIN	SPI enable input to LMK0482x
TPB4	LMK_RESET	LMK PIN	RESET pin to LMK0482x
TPB5	RSV_DIG	n/a	Reserved
TP24	GND	GND	Ground Reference for EVM

3.3 EVM Clock Configuration

The EVM should be shipped with jumpers setting the LMK04826 clocking device (U2) in clock distribution mode. In this configuration shown in Figure 3, the LMK04826 acts as a clock buffer/divider on the external input clock to SMA J75, LMK_CLKIN1. For LVDS mode, this input clock should be set to the desired system clock required by the ADS52J90. To support the JESD204B interface, this input clock should be set to 1/40 the SerDes line rate when the line rate is above 1Gbps and 1/10 the SerDes line rate when the line rate is below 1Gbps. Put another way, the SerDes lane rate will be 10x the reference clock when the calculated lane rate is below 1Gbps and will be 40x the reference clock when the calculated lane rate is above 1Gbps. The HSDCpro GUI will report both the calculated lane rate and the required reference clock each time the user changes the *Output Data Rate* value in the GUI. Figure 4 and Figure 5 show examples of the message when lane rate is 40x the reference clock and when the lane rate is 10x the reference clock, respectively. Configuration scripts for both 10x rate and 40x rate are provided in folders with the appropriate suffix appended to the folder names.

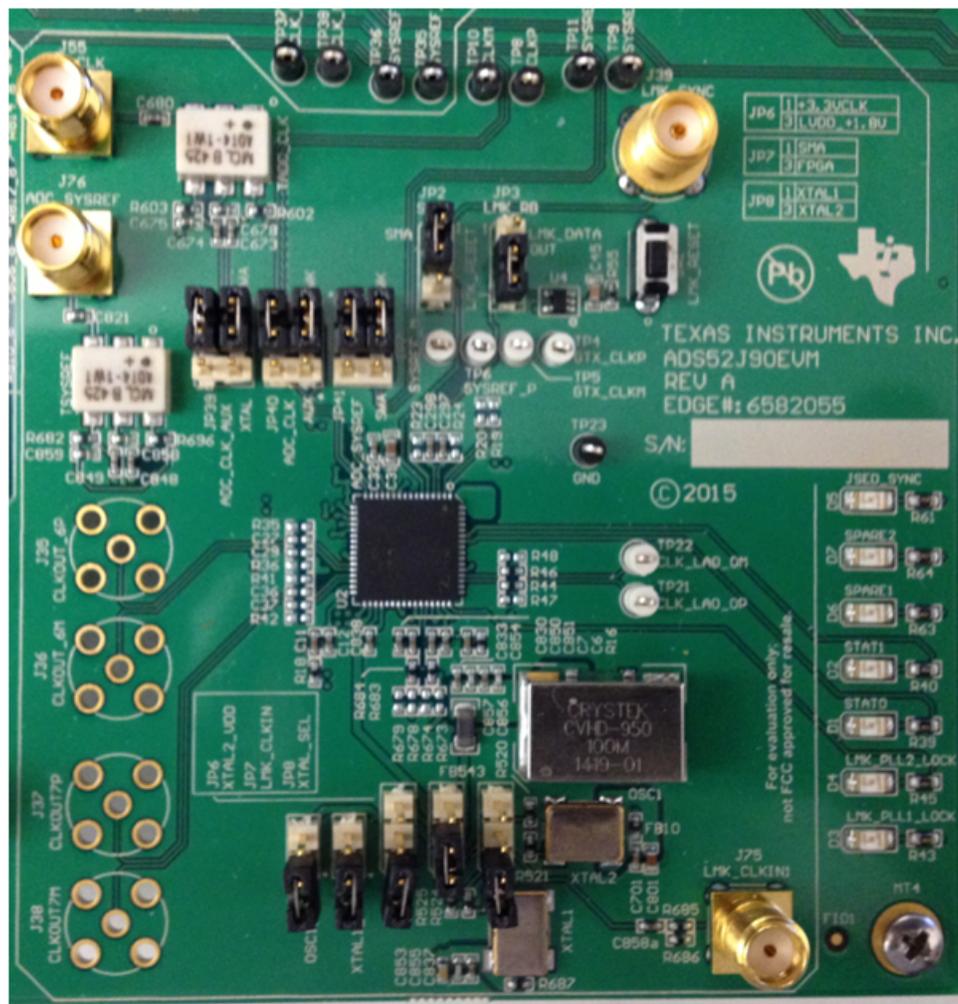
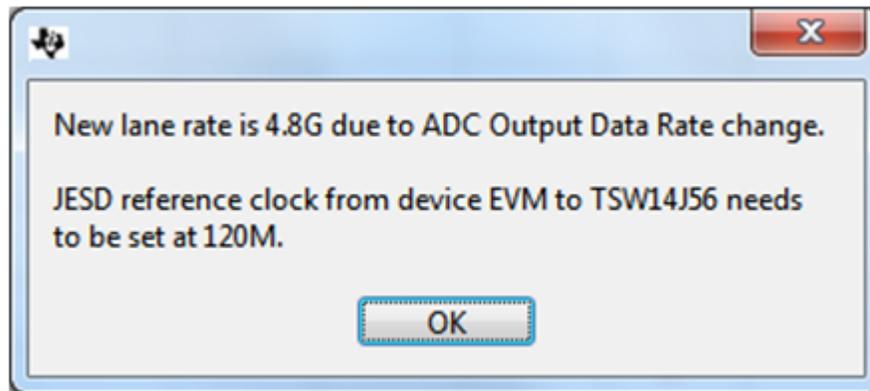
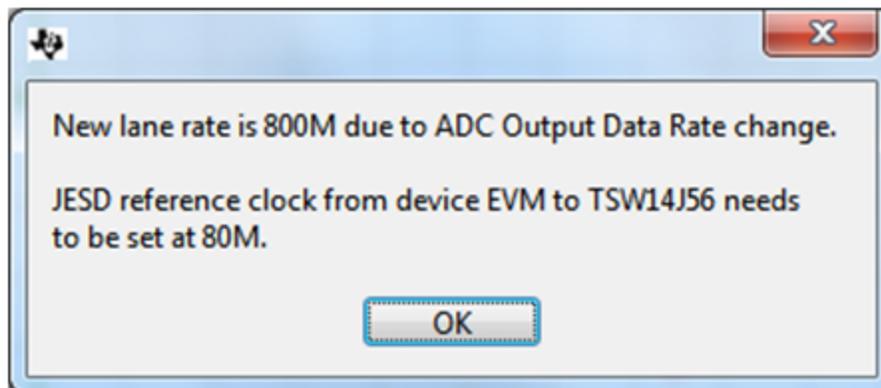


Figure 3. Clock Config: LMK CDM Mode


Figure 4. HSDCpro 40x Lane Rate Message

Figure 5. HSDCpro 10x Lane Rate Message

4 Quick Test LVDS Interface

This section outlines the following:

- EVM Layout and Hardware Setup
- How to capture a RAMP and Sinusoidal Inputs for 16ch mode
- How to use scripts to measure all LVDS modes supported by the device

4.1 EVM Layout and Hardware Setup

The ADS52J90 supports 3 modes of operation with respect to the analog inputs: (1) 32-channel mode, (2) 16-channel mode, (3) 8-channel mode. [Figure 6](#) shows the breakdown of the analog channels on the EVM. Testing 32-channel mode is done using all Channels 1-24 on the EVM. Testing 16-channel mode is done using the odd channels of 1-23 on the EVM. These are the vertically-mounted SMAs. Testing 8-channel mode is done using Channels 7 and 8. Channel 7 is configured to accept a differential input to **SMA_CH7A** and **SMA_CH7** whereas Channel 8 is configured to convert a signal ended input to **SMA_CH8** into a differential signal via an amplifier.

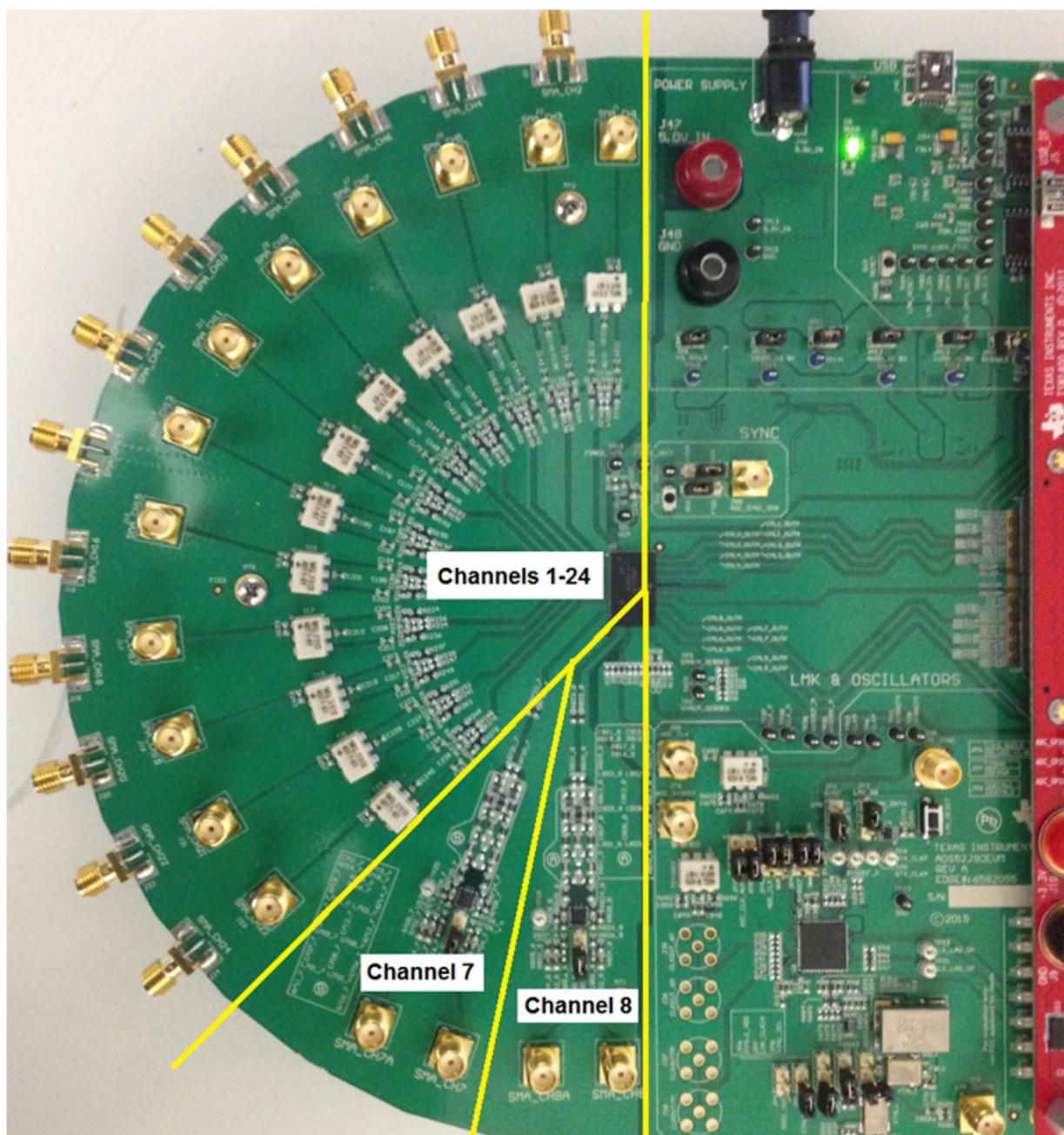


Figure 6. ADS52J90 EVM Analog Channels

The connections shown in [Figure 7](#) should be made for proper hardware setup.

NOTE: Testing the LVDS interface between the ADS52J90 EVM and the TSW1400 EVM can be performed using a RAMP test pattern generated within the ADS52J90 device in lieu of the signal source listed in item 7, in the following steps.

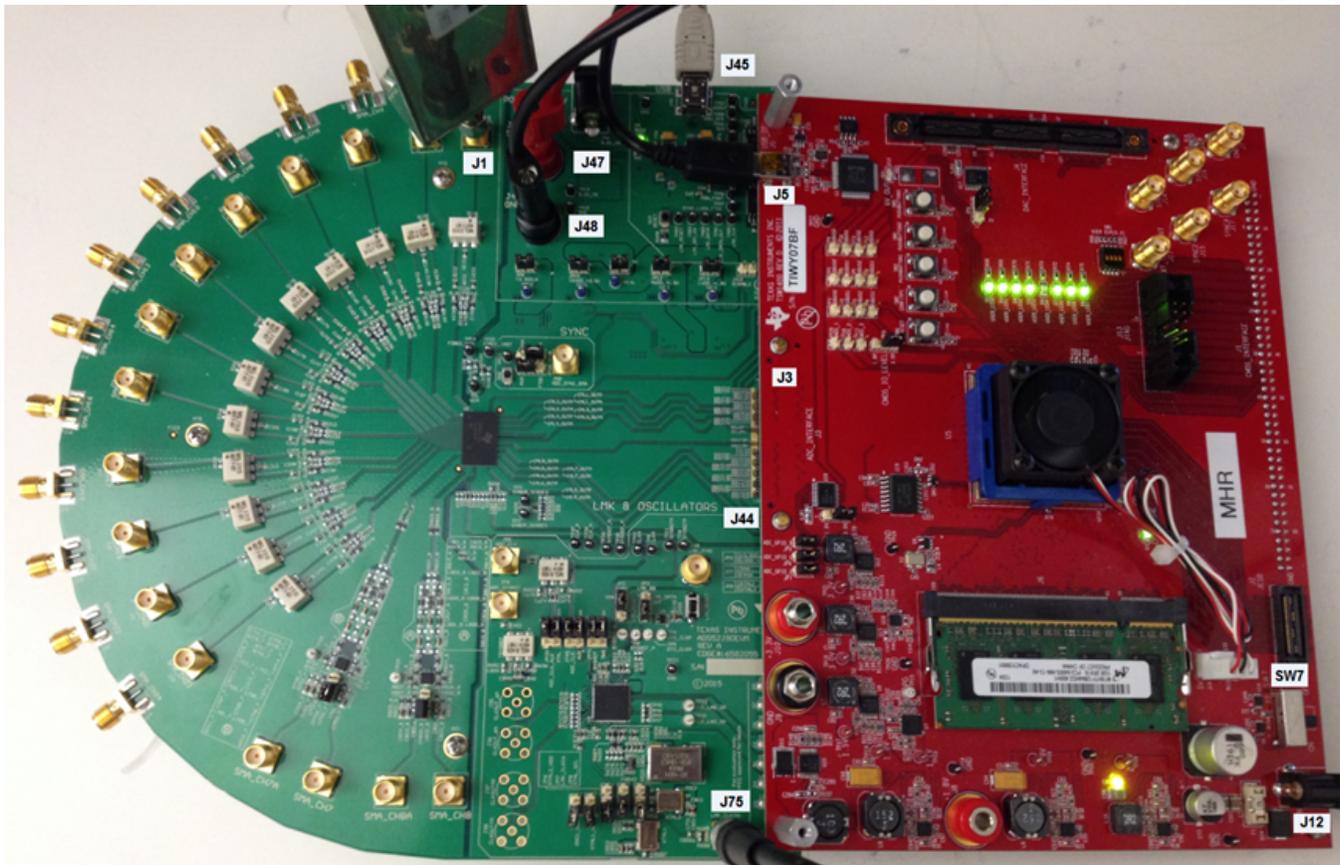


Figure 7. TSW1400 and ADS52J90 Setup

1. Mate the TSW1400 EVM at connector J3 to the ADS52J90 EVM at connector **J44** through the high speed ADC interface connector.

NOTE: The two standoffs closest to J3 on the TSW1400 must be removed. Also, the EVM kit provides two supplementary standoffs that should be added to the remaining two standoffs so that the two EVMs are properly aligned.

2. Connect a DC +5-V power supply output of the provided AC-to-DC power supply to **J12 (+5V_IN)** of the TSW1400 EVM and the input of the power supply cable to a 110–230 VAC source.
3. Ensure that **SW7** is set to ON position on TSW1400.
4. Connect a DC +5-V power supply across banana jacks **J47** and **J48** on the ADS52J90 EVM. Alternatively, test points **TP13** and **TP15** can be used if alligator clip leads are available.
5. Connect the USB cable from the PC to **J45 (USB)** of the ADS52J90 EVM.
6. Connect the USB cable from the PC to **J5 (USB_IF)** of the TSW1400 EVM.

NOTE: TI recommends that the PC USB port be able to support USB2.0. If unsure, always chose the USB ports at the back of the PC chassis over ones located on the front or sides.

- Supply an analog input signal to SMA J1 (SMA_CH1) of the ADS52J90 EVM (such as +16 dBm, 5.0 MHz).

NOTE: A low phase noise signal source (such as R&S SMA100A) with a band pass filter is needed in order to measure SNR values reported in the datasheet. Also, the instrument should have a 10-MHz back panel reference port allowing for coherent sampling when phase locked with the sampling clock signal.

- Supply a reference clock to SMA J75 (LMK_CLKIN1) of the ADS52J90 EVM that is equal to the desired system clock frequency. In the following examples 65 MHz is used as it supports all channel modes of the device.

NOTE: A low phase noise, highly linear, signal source (such as RS SMA100A) is needed in order to measure SNR values reported in the datasheet. Also, the instrument should have a 10-MHz back panel reference port allowing for coherent sampling when phase locked with the analog input clock signal

4.2 Capturing Ramp Test Pattern and Sinusoidal Input

- With the hardware setup shown in Figure 7 established, launch the *High Speed Data Converter Pro GUI*. The GUI should automatically detect the serial number of the TSW1400 EVM connected as shown in Figure 8. Click on OK.

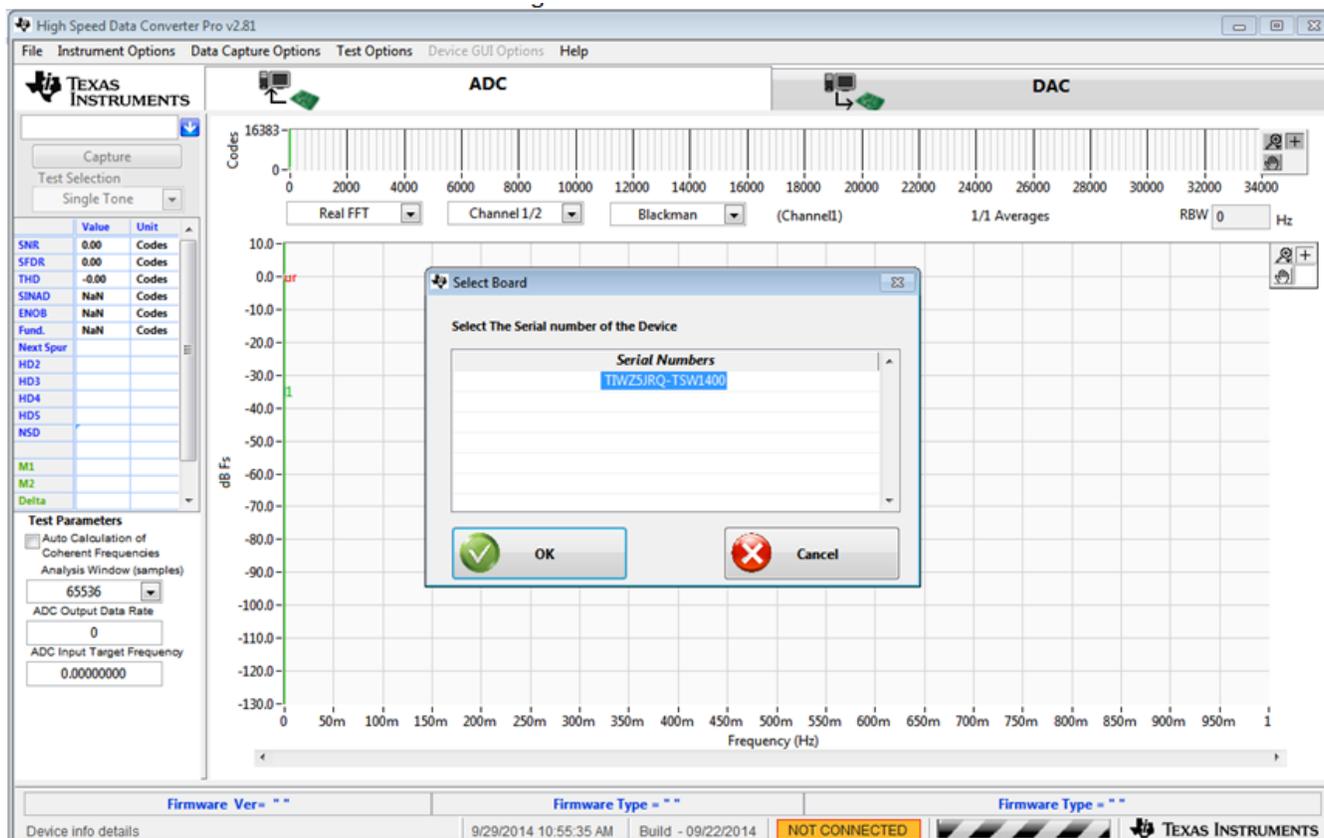


Figure 8. TSW1400 GUI Setup (a)

The message shown in [Figure 9](#) will appear. Click OK.



Figure 9. TSW1400 GUI Setup (b)

If instead, the message shown in [Figure 10](#) appears, it indicates that the USB connection to the TSW1400 EVM is not present. Click *OK*, then establish a USB connection and repeat [step 1](#).

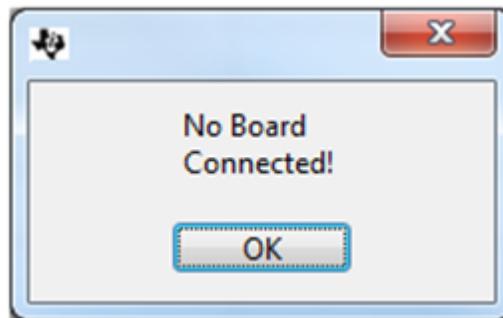


Figure 10. TSW1400 GUI Setup (c)

2. Select a device firmware to load in the FPGA by clicking on the blue arrow in the upper left corner of the *HSDCpro* GUI. Scroll down and select *ADS52J90* as shown in [Figure 11](#).

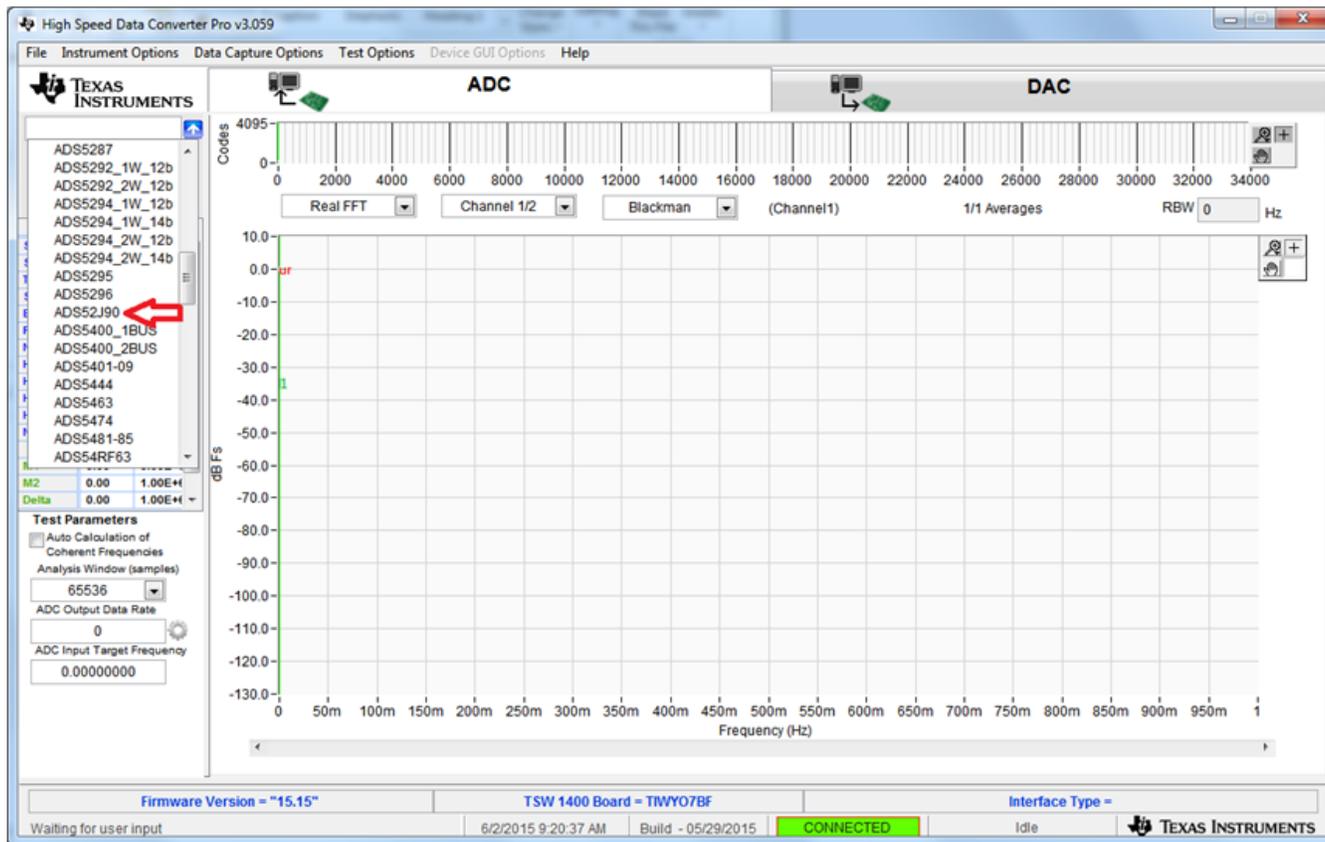


Figure 11. TSW1400 GUI Setup (d)

Click the Yes button to update the ADC firmware on the TSW1400 FPGA as depicted in [Figure 12](#).

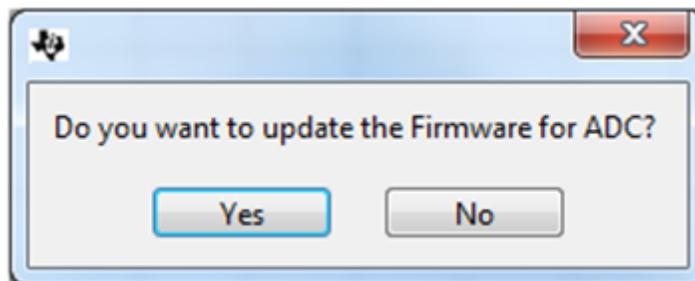


Figure 12. TSW1400 GUI Setup (e)

While the firmware is being loaded into the TSW1400 FPGA, the graphic shown in Figure 13 will appear after which the device GUI (HMC-DAQ) will launch as shown in Figure 14.

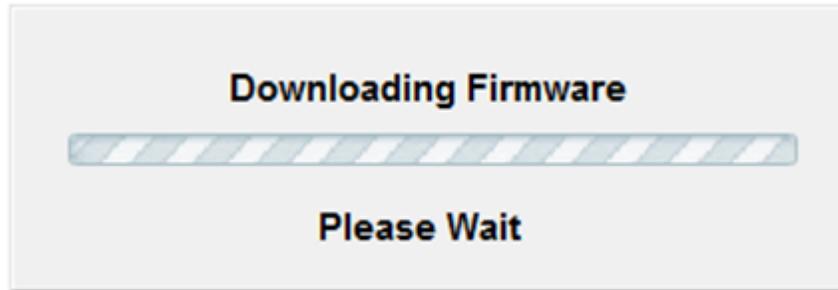


Figure 13. TSW1400 GUI Setup (f)

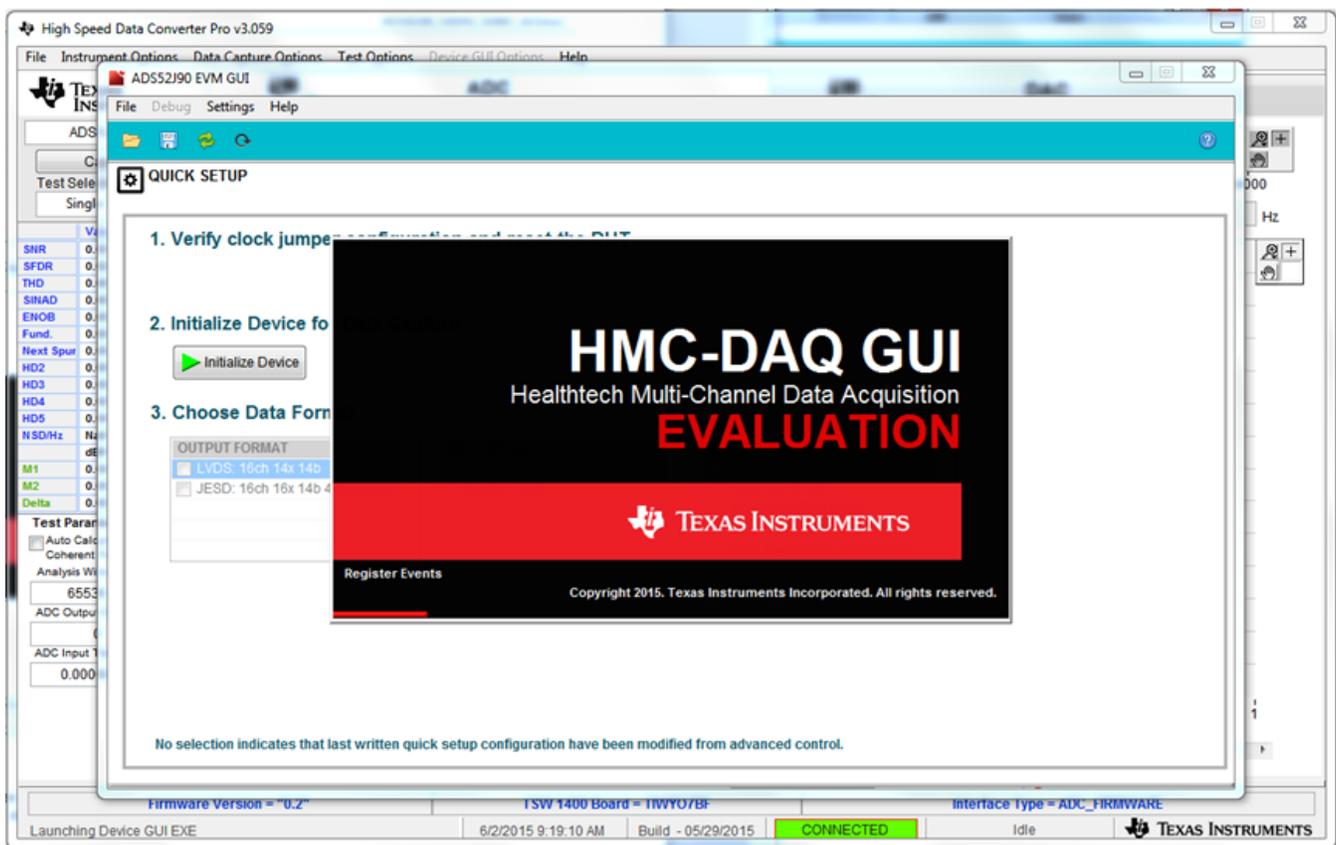


Figure 14. HMC-DAQ GUI Setup (a)

If the GUI recognizes that hardware is connected, HMC-DAQ will show HW CONNECTED in green in the border of the GUI as shown in Figure 15.

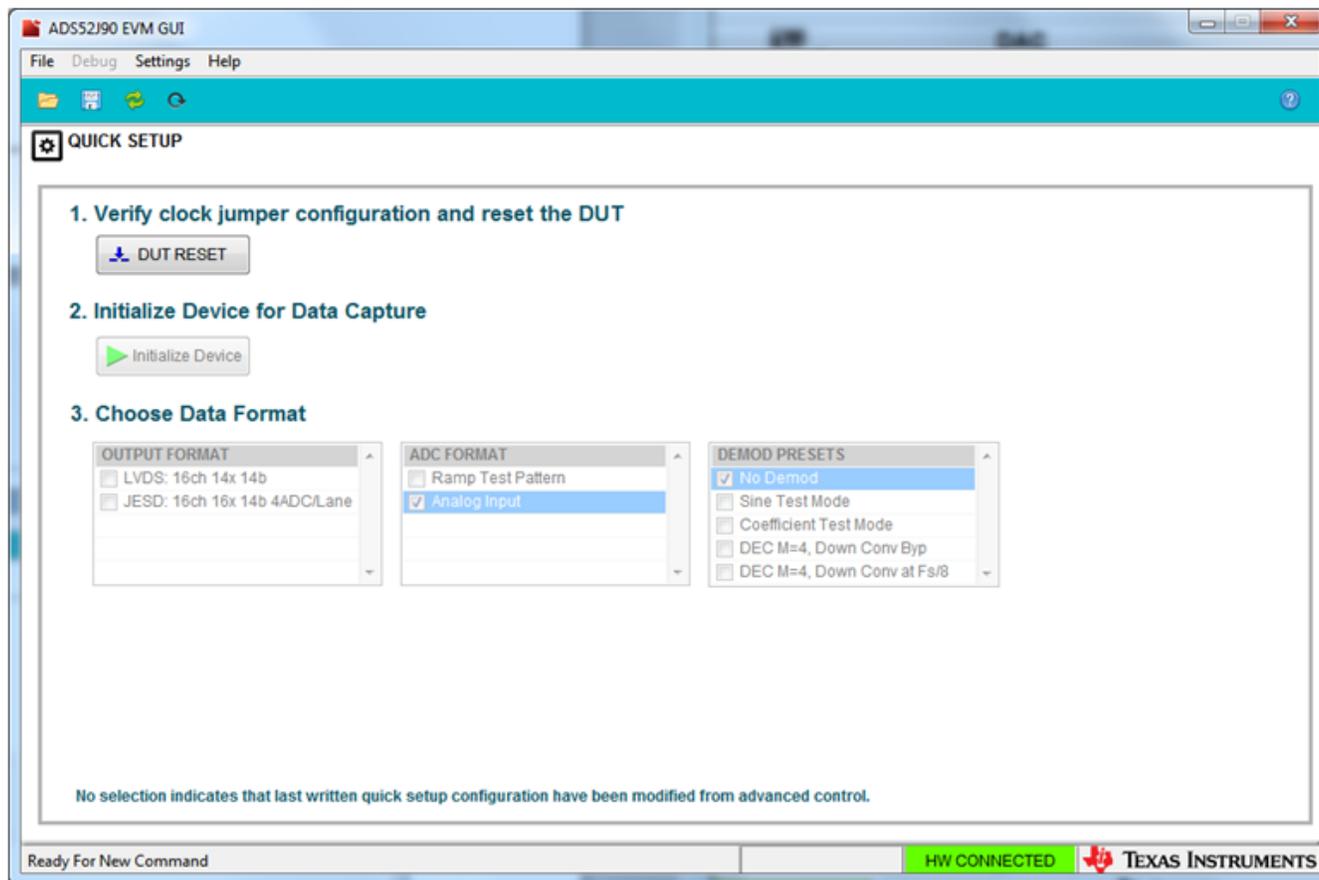


Figure 15. HMC-DAQ GUI Setup (b)

If instead, the message shown in Figure 16 appears, it indicates a USB connection issues between the PC and the ADS52J90 EVM. Close HSDCpro, establish USB connections and restart from procedure 1.

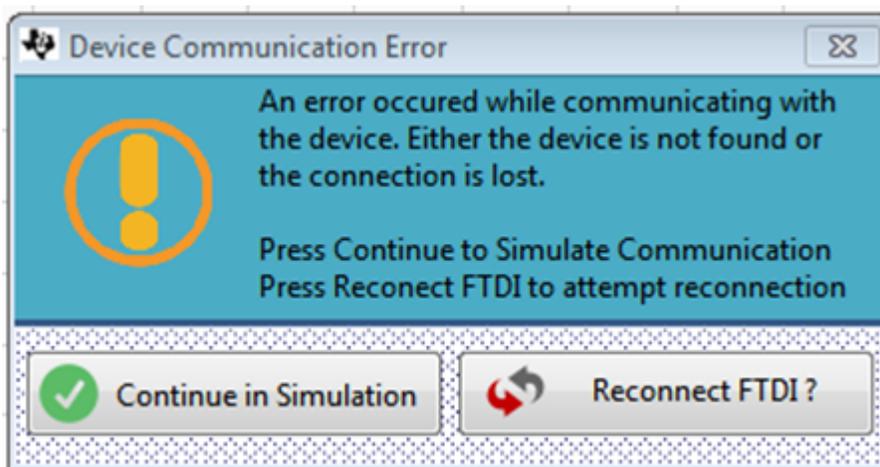


Figure 16. HMC-DAQ GUI Setup (c)

3. At this point there should be two GUI's running and connected, HSDCpro and HMC-DAQ which are communicating behind the scenes. Anytime the ADS52J90 device configuration is updated, HSDCpro is informed and the appropriate firmware updates are done automatically. To capture a RAMP test pattern in LVDS, 16-channel, 14 bit, 14x serialization configuration, do the following as shown in Figure 17:
 - (a) Press **DUT RESET** button
 - (b) Press **Initialize Device** button
 - (c) Check the box next to **LVDS 16ch 14x 14b**
 - (d) Check the box next to **Ramp Test Pattern**

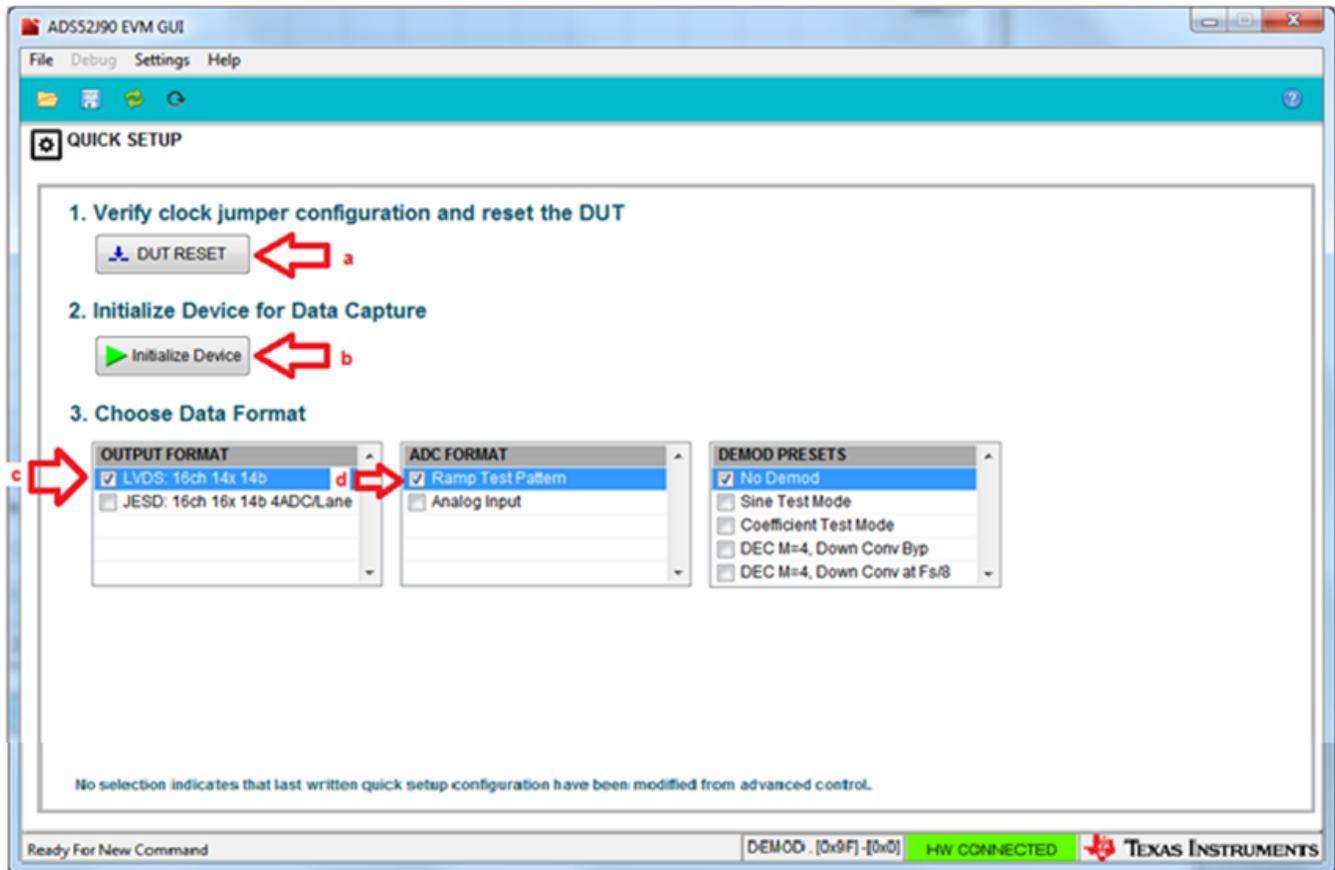


Figure 17. HMC-DAQ GUI Setup (d)

4. Return to HSDCpro GUI and perform the following steps as shown in Figure 18 .
 - (a) Change the plot type from *Real FFT* to *Codes*
 - (b) Enter 65M in the field labeled *ADC Output Data Rate*
 - (c) Press the *Capture* button.

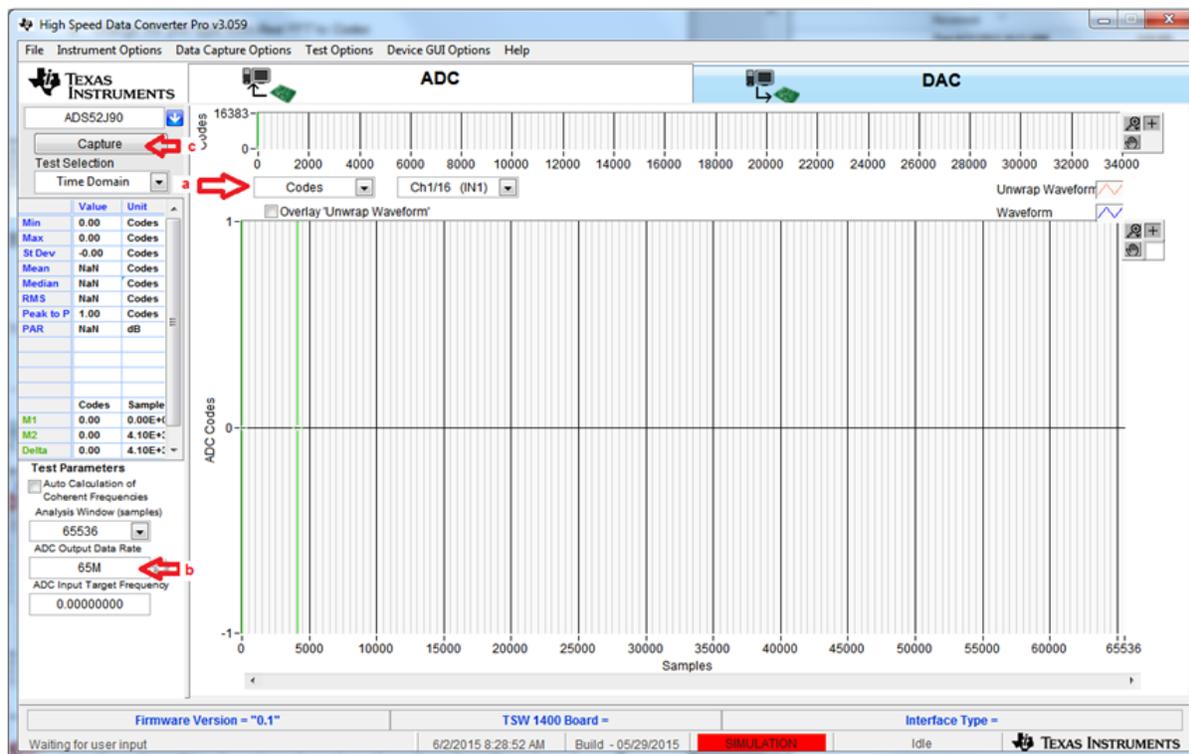


Figure 18. ADS52J90 16-Channel RAMP Capture (a)

A RAMP capture should appear as shown in Figure 19.

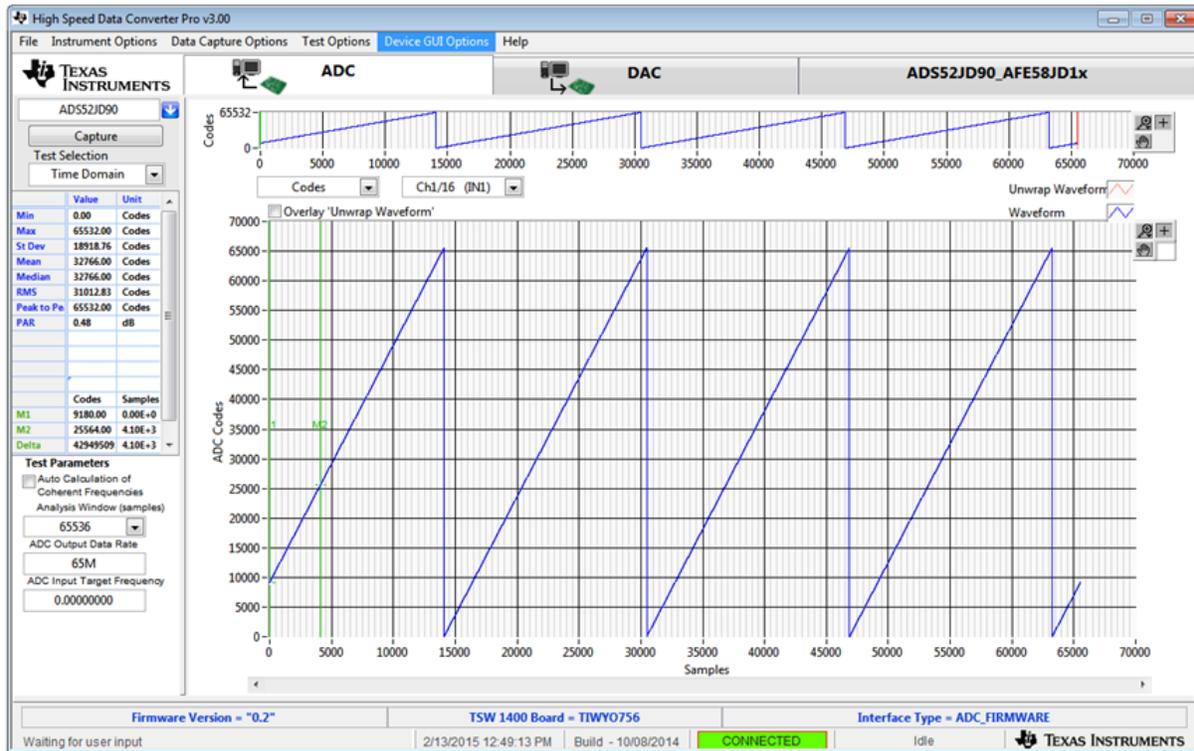


Figure 19. ADS52J90 16-Channel RAMP Capture (b)

By default, Ch1 (16CH) is the first channel displayed. Use the drop-down menu shown in Figure 20 to view any one 16 channels.

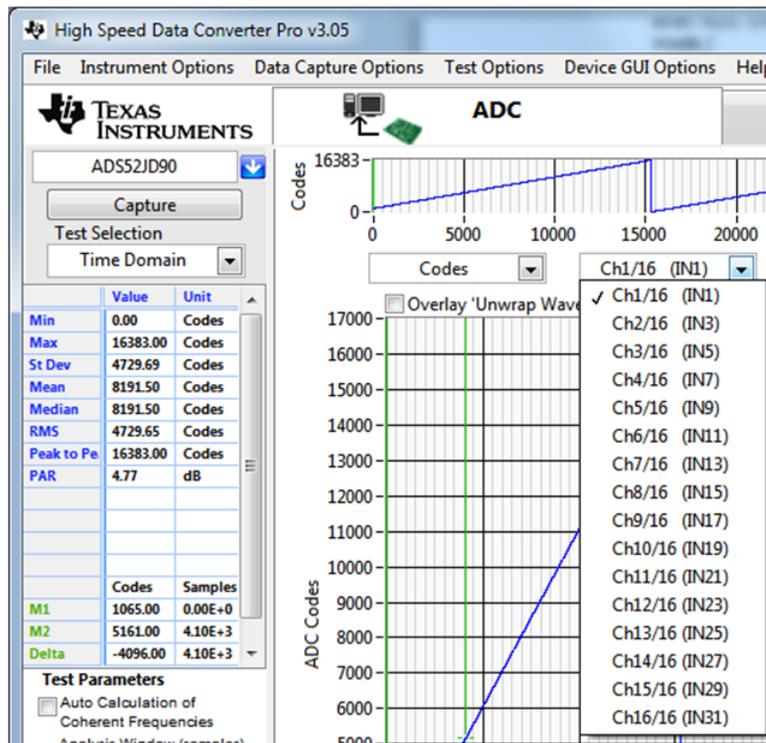


Figure 20. ADS52J90 16-Channel RAMP Capture (c)

Zooming into the waveform and changing the plot graphic (using the buttons to the upper right of graph), as shown in Figure 21, is recommended to confirm that the RAMP waveform is correct with each subsequent sample incremented 1 ADC code until max code of $(2^N) - 1$ is reached, where N is ADC resolution.

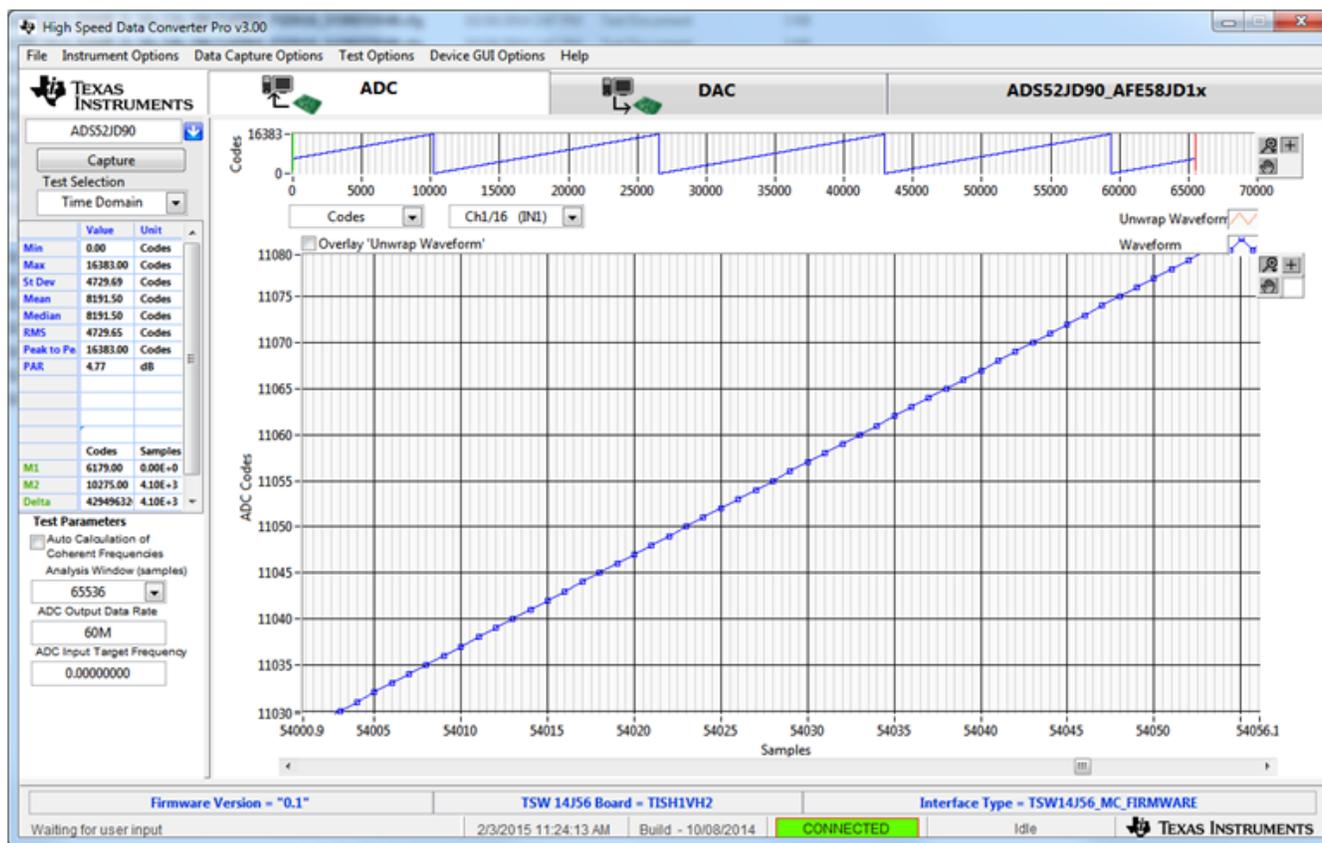


Figure 21. ADS52J90 16-Channel RAMP Capture (d)

- To capture a sinusoidal input, return to the HMC-DAQ GUI and press the check box next to **Analog Input** as shown in Figure 22.

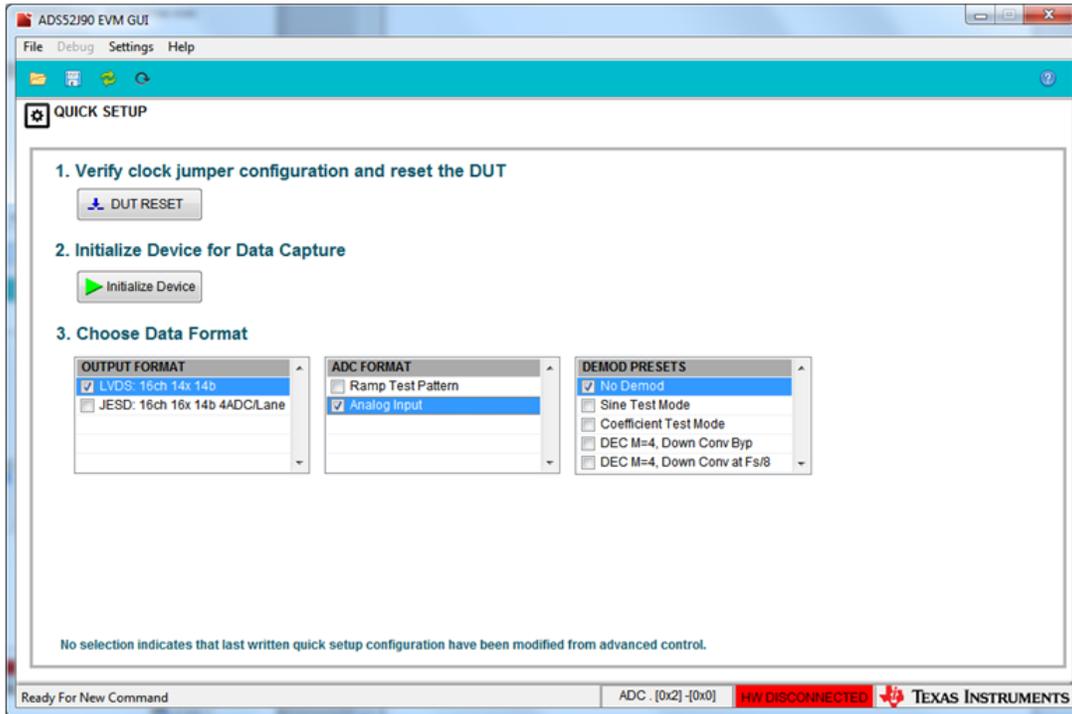


Figure 22. ADS52J90 16-Channel SINE Capture (a)

6. Return to HSDCpro GUI and perform the following (as illustrated in Figure 23):
 - (a) Change the plot type from Codes to Real FFT
 - (b) Enter 65M in the field labeled ADC Output Data Rate
 - (c) Enter 5.0M in the field labeled ADC Input Target Frequency (or set to the desired input that is being provided to SMA J1, SMA_CH1, as described in (Section 4.1).
 - (d) Press the Capture button.

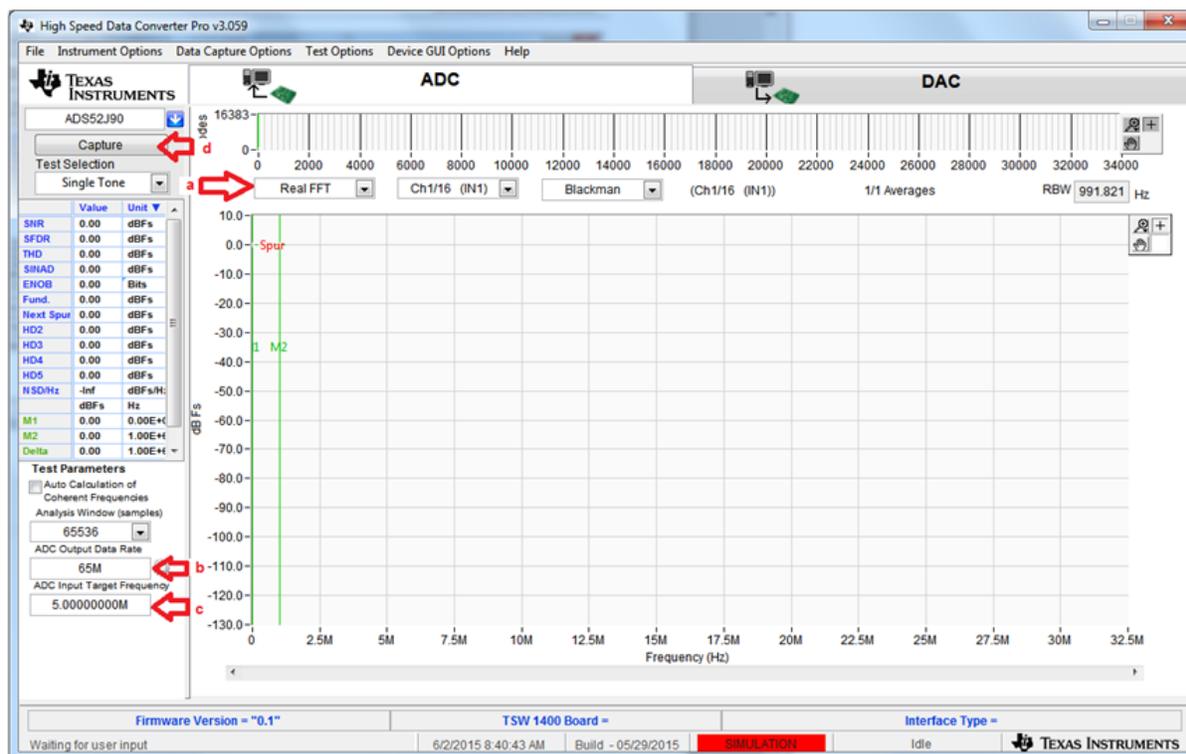


Figure 23. ADS52J90 16-Channel SINE Capture (b)

A capture similar to that shown in Figure 24 should appear.

NOTE: The analog input level was adjusted and a recapture done iteratively until the **Fund.** value was approximately -1 dBFs.

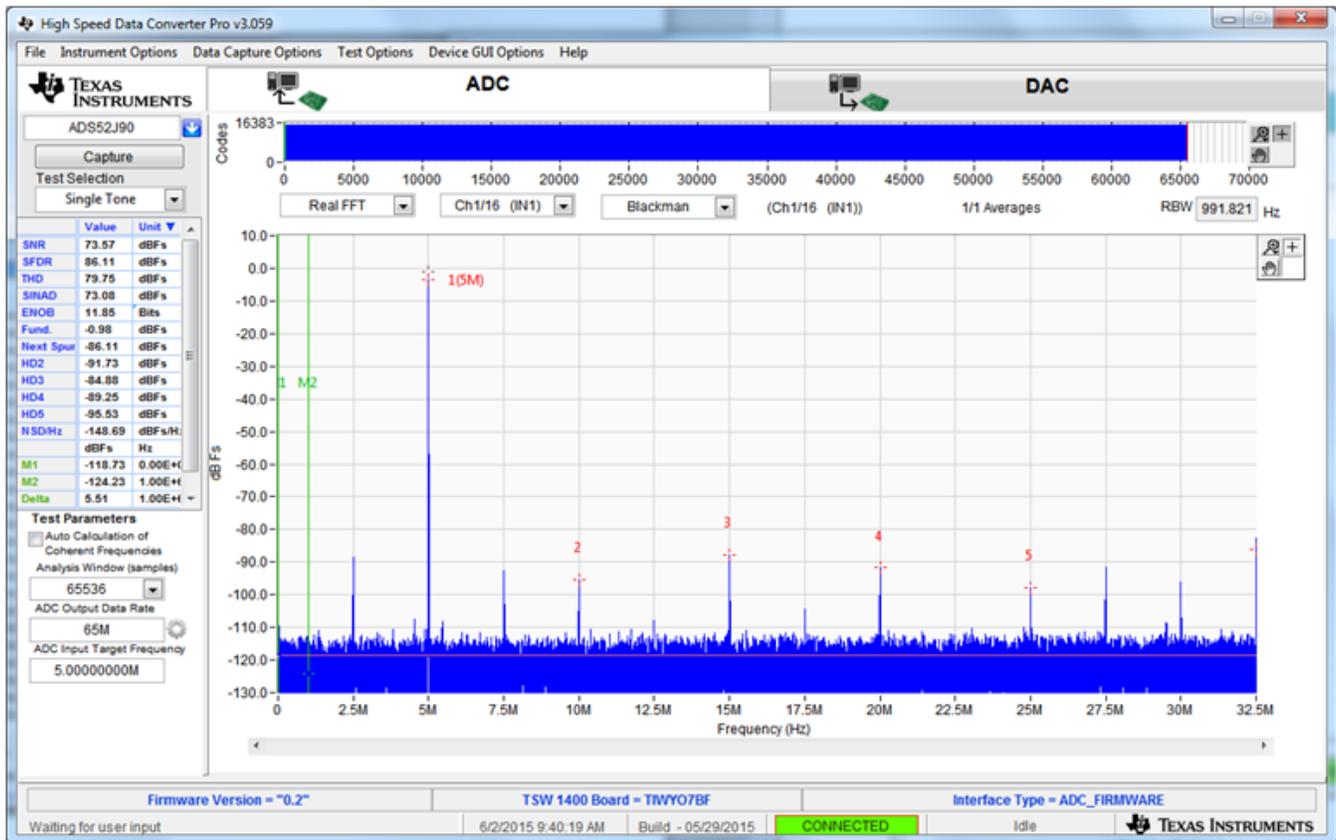


Figure 24. ADS52J90 16-Channel SINE Capture (c)

By default, *Ch1 (16CH)* is the first channel displayed. Use the drop-down menu to view any one 16 channels.

NOTE: The vertically-mounted SMAs on the EVM are the analog inputs to the odd ADC channels while the side-mounted SMAs are the analog inputs to the even ADC channels. Per the datasheet, only odd channels are being sampled when in 16-channel mode.

4.3 Testing All Modes of the Device

In addition to the quick start buttons provided on the **QUICK SETUP** tab of HMC-DAQ GUI, there are scripts to configure the device for all supported modes. To access the scripts, click on the folder icon in the upper left corner of the HMC-DAQ GUI, as shown in [Figure 25](#).

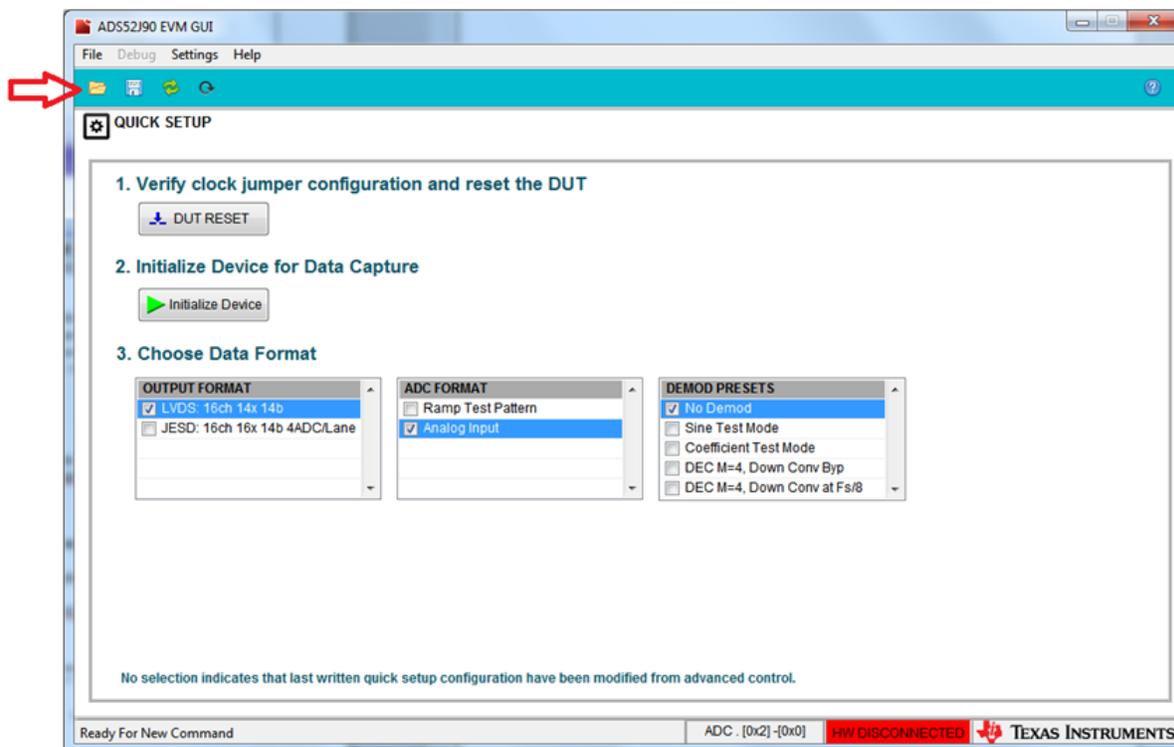


Figure 25. ADS52J90 All Supported Configs

Select anyone of 24 configurations provided and then press *Capture* in HSDCpro. When testing 32-channel mode, ensure that the **ADC Output Data Rate** in HSDCpro is set to half the system clock being provided to the device. For example, if 65 MHz is supplied to **J75** then this value should be set to 32.5 MHz. When testing 8-channel or 16-channel modes, the **ADC Output Data Rate** should be set to the value of the system clock provided to the DUT.

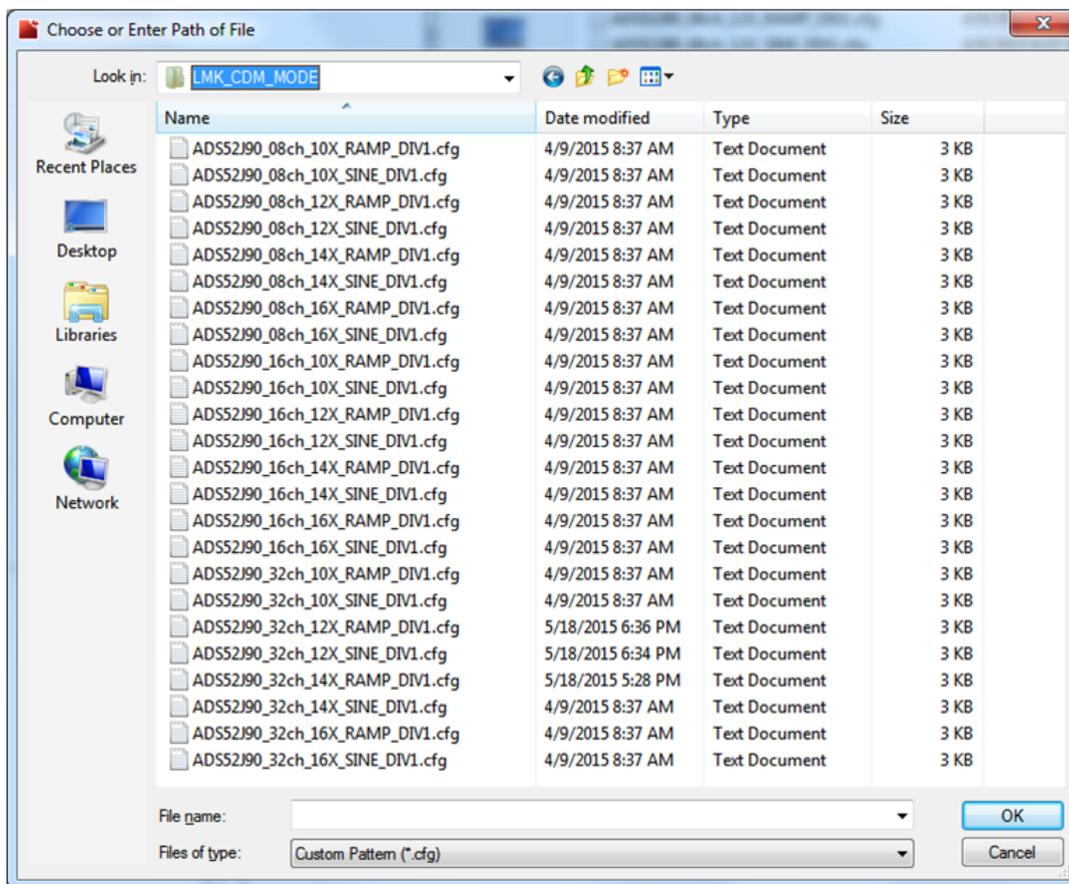


Figure 27. ADS52J90 All Supported Configs (c)

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- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

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2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
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